

IN THE CLAIMS:

Please cancel claim 13 without prejudice to or disclaimer of the subject matter recited therein.

Please amend claims 1 and 6 as follows:

LISTING OF CURRENT CLAIMS

1. (Currently Amended) A thin type camera module comprising:

a fixing board having a top surface and a recession indented from the top surface, wherein the recession having an undersurface;

an imaging-sensing semiconductor assembly comprising a COF (chip-on film) wiring film and an image sensing chip, wherein the COF wiring film has a surface, a window and a plurality of connecting ends disposed on the surface of the COF wiring film around the window, the image sensing chip has a photosensitive surface corresponding to the window^{[[,]]} and a bottom surface attached to the undersurface of the recession, and a plurality of bumps are formed on peripherals of the photosensitive surface, the image sensing chip is flip-chip mounted on the COF wiring film to electrically connect the bumps with the connecting ends; and

a lens holder for connecting a camera lens, wherein the lens holder has a light-pervious channel and is connected with the fixing board to form ^{[[a]]} an airtight space for sealing the image sensing chip, and the photosensitive surface of the image sensing chip is corresponding to the light-pervious channel for capturing image.

2. (Original) The thin type camera module in accordance with claim 1, further comprising at least an electric device electrically connected with the COF wiring film.

3. (Original) The thin type camera module in accordance with claim 2, wherein the electric device is a passive component.

4. (Original) The thin type camera module in accordance with claim 2, wherein the COF wiring film formed a module circuit electrically connecting the electric device.

5. (Original) The thin type camera module in accordance with claim 4, wherein the module circuit is formed on an extending surface of the COF wiring film without being covered by the lens holder.
6. (Currently Amended) The thin type camera module in accordance with claim 1, further ~~comprising~~ comprising a sealant layer ~~is formed~~ around the window of the COF wiring film for enclosing the bumps of the image sensing chip.
7. (Original) The thin type camera module in accordance with claim 6, wherein the sealant layer is an anisotropic conductive film (ACF).
8. (Original) The thin type camera module in accordance with claim 6, wherein the sealant layer is a non-conductive film (NCF).
9. (Original) The thin type camera module in accordance with claim 6, wherein the sealant layer is transparent thermosetting compound.
10. (Original) The thin type camera module in accordance with claim 1, wherein the COF wiring film has at least a conductive via electrically connecting the connecting ends.
11. (Original) The thin type camera module in accordance with claim 1, wherein the lens holder comprises a filter aligning with the light-pervious channel.
12. (Original) The thin type camera module in accordance with claim 1, further comprising a camera lens connected with the lens holder.
13. (Cancelled)
14. (Original) The thin type camera module in accordance with claim 1, wherein the airtight space is in vacuum state.

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15. (Original) The thin type camera module in accordance with claim 1, wherein the airtight space filled with inert gas.